Isolation Voltage	V_{iso}	3750 "	Vrms
Operating Temperature	T_{opr}	-55~+110	
Storage Temperature	T_{stg}	-55~+125	
Soldering Temperature	T_{sol}	260	

NOTE1:100 s pulse, 100Hz frequency
NOTE2:AC for 1minute, R.H.=40~60%

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F=10mA	-	-	1.4	V
	Reverse Current	I_R	V_R=6V	-	-	1	A
	Terminal Capacitance	C_t	V=0, f=1kHz	-	10	-	pF
Output	Collector-Emitter dark current	I_{CEO}	V_{CE}=10V, I_F=0	-	-	100	nA
	Collector-Emitter breakdown voltage	BV_{CEO}	I_C=0.1mA I_F=0	40	-	-	V
	Emitter-Collector breakdown voltage	BV_{ECO}	I_E=0.1mA I_F=0	6	-	-	V
Transfer Characteristics	Current transfer ratio	CTR '	I_F=1mA V_{CE}=2V	600	-	7500	%
	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	I_F=20mA I_C= 5mA	-	0.8	1	V
	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	10^{12}	10^{14}	-	
	Floating Capacitance	C_{IO}	V=0, f=1MHz	-	0.4	1	pF
	Cut-off Frequency	f_c	V_{CE}=5V, I_C=10mA R_L -3dB	-	1	-	kHz
	Rise Time	t_r	V_{CE}=2V, I_C=10mA R_L	-	95	300	s
	Fall Time	t_f		-	84	250	s

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

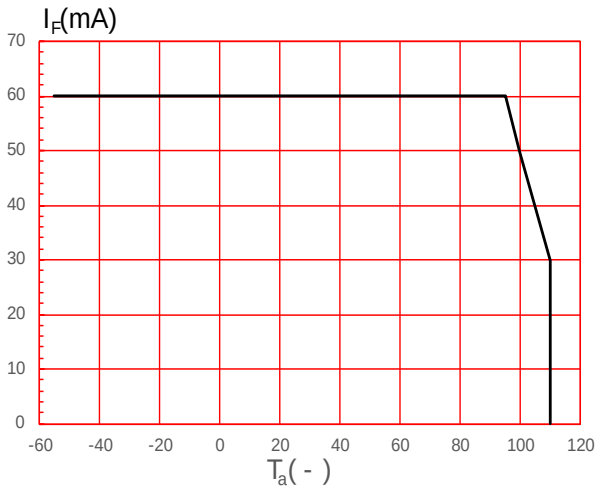


FIG.2: Collector Power Dissiption vs. Ambient Temperature



FIG.7: Normalized Current Transfer Ratio vs.

Test Circuits

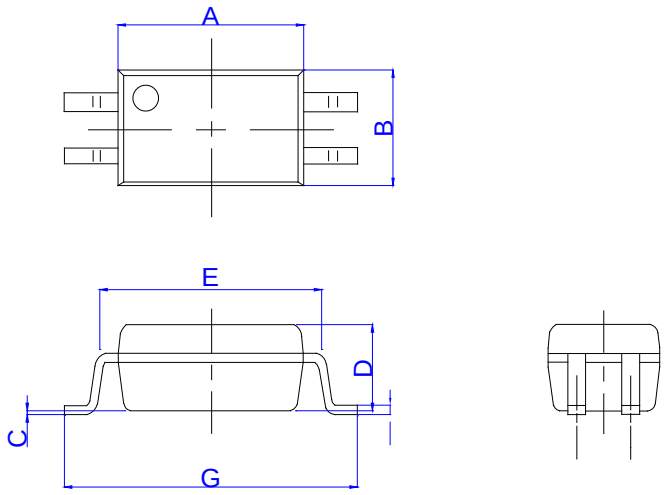
FIG.12: Test Circuits of Response Time

FIG.13: Curves of Response Time

FIG.14: Test Circuits of Frequency Response

Package Dimension (Unit: mm)

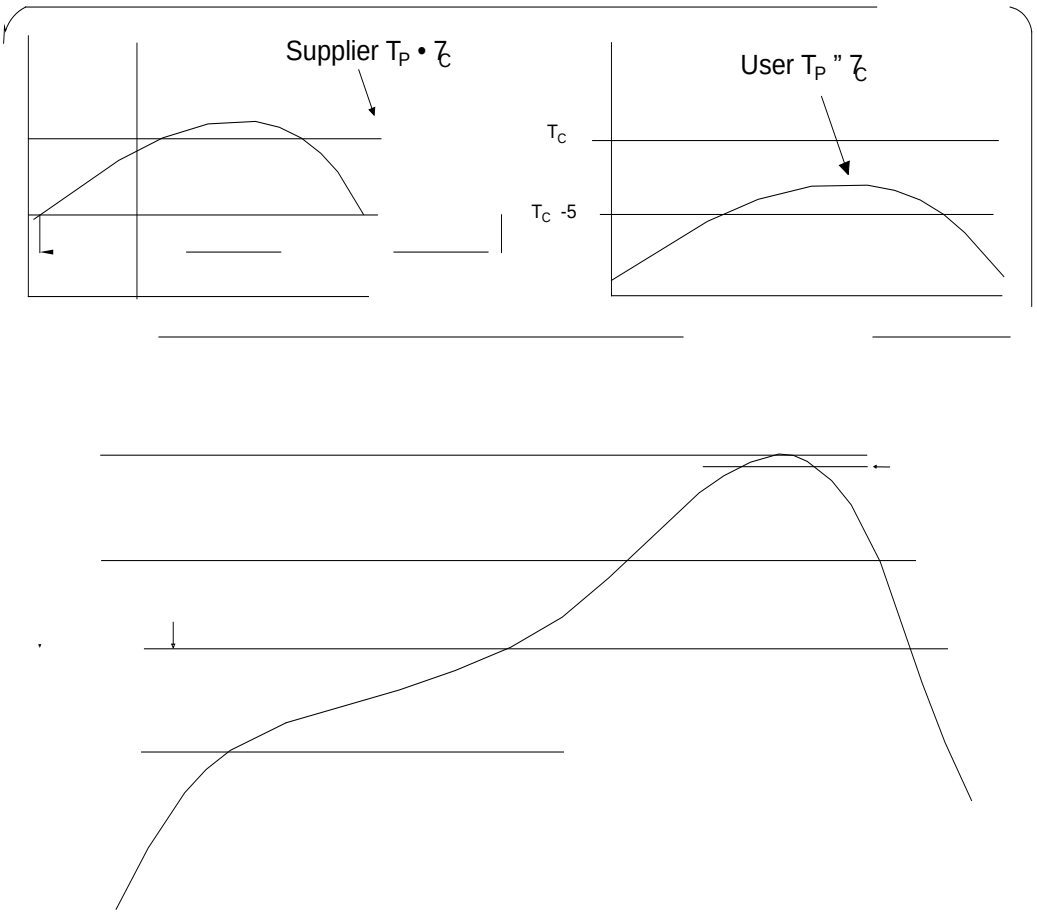
Standard SSOP4 Type:



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1

REFLOW INFORMATION (Pb-free)



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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